



ASMNUT.124C1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Basol et al.
Appl. No. : 10/663,318
Filed : September 16, 2003
For : CONDUCTIVE STRUCTURE
FABRICATION PROCESS USING
NOVEL LAYERED STRUCTURE
AND CONDUCTIVE
STRUCTURE FABRICATED
THEREBY FOR USE IN MULTI-
LEVEL METALLIZATION

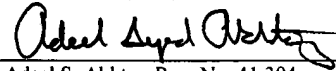
Examiner : Thao X. Le
Group Art Unit : 2814

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

February 24, 2005

(Date)


Adeel S. Akhtar, Reg. No. 41,394

RESPONSE TO OFFICE ACTION

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed on November 29, 2004, please amend the above-captioned application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.